

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S31 1	936814	substrate	US-PGPUB; USPAT	ADJ	ON	2007/02/06 13:41
S31 2	618518	semiconductor	US-PGPUB; USPAT	ADJ	ON	2007/02/06 13:41
S31 3	13086	plating adj method	US-PGPUB; USPAT	ADJ	ON	2007/02/06 13:41
S31 4	12494	interconnect near metal	US-PGPUB; USPAT	ADJ	ON	2007/02/06 13:42
S31 5	2403755	via or trench or recess	US-PGPUB; USPAT	ADJ	ON	2007/02/06 13:42
S31 6	3447643	narrow or small or thin or pinched or close	US-PGPUB; USPAT	ADJ	ON	2007/02/06 13:43
S31 7	1728052	broad or wide or deep	US-PGPUB; USPAT	ADJ	ON	2007/02/06 13:43
S31 9	1149065	fill or filled or filling	US-PGPUB; USPAT	ADJ	ON	2007/02/06 13:44
S32 0	746524	deposit or deposited or depositing	US-PGPUB; USPAT	ADJ	ON	2007/02/06 13:45
S32 1	363367	S311 and S312	US-PGPUB; USPAT	ADJ	ON	2007/02/06 13:45
S32 2	10349	S311 and S313	US-PGPUB; USPAT	ADJ	ON	2007/02/06 13:46
S32 3	6290	S312 and S313	US-PGPUB; USPAT	ADJ	ON	2007/02/06 13:46
S32 4	5741	S311 and S312 and S313	US-PGPUB; USPAT	ADJ	ON	2007/02/06 13:46
S32 5	10175	S321 and S314	US-PGPUB; USPAT	ADJ	ON	2007/02/06 13:47
S32 6	184	S322 and S314	US-PGPUB; USPAT	ADJ	ON	2007/02/06 13:47
S32 7	183	S323 and S314	US-PGPUB; USPAT	ADJ	ON	2007/02/06 13:47
S32 8	180	S324 and S314	US-PGPUB; USPAT	ADJ	ON	2007/02/06 13:47
S32 9	8494	S325 and S315	US-PGPUB; USPAT	ADJ	ON	2007/02/06 13:48
S33 0	171	S326 and S315	US-PGPUB; USPAT	ADJ	ON	2007/02/06 13:48
S33 1	171	S327 and S315	US-PGPUB; USPAT	ADJ	ON	2007/02/06 13:48
S33 2	169	S328 and S315	US-PGPUB; USPAT	ADJ	ON	2007/02/06 13:49

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S33 3	7331	S329 and S316	US-PGPUB; USPAT	ADJ	ON	2007/02/06 13:49
S33 4	161	S330 and S316	US-PGPUB; USPAT	ADJ	ON	2007/02/06 13:49
S33 5	160	S331 and S316	US-PGPUB; USPAT	ADJ	ON	2007/02/06 13:49
S33 6	159	S332 and S316	US-PGPUB; USPAT	ADJ	ON	2007/02/06 13:50
S33 7	6730	S333 and (S319 or S320)	US-PGPUB; USPAT	ADJ	ON	2007/02/06 13:51
S33 8	157	S334 and (S319 or S320)	US-PGPUB; USPAT	ADJ	ON	2007/02/06 13:51
S33 9	156	S335 and (S319 or S320)	US-PGPUB; USPAT	ADJ	ON	2007/02/06 13:51
S34 0	155	S336 and (S319 or S320)	US-PGPUB; USPAT	ADJ	ON	2007/02/06 13:52
S34 1	3571	S337 and S317	US-PGPUB; USPAT	ADJ	ON	2007/02/06 13:52
S34 2	98	S338 and S317	US-PGPUB; USPAT	ADJ	ON	2007/02/06 14:10
S34 3	97	S339 and S317	US-PGPUB; USPAT	ADJ	ON	2007/02/06 13:52
S34 4	97	S340 and S317	US-PGPUB; USPAT	ADJ	ON	2007/02/06 13:52
S34 5	60	S341 and "205".clas.	US-PGPUB; USPAT	ADJ	ON	2007/02/06 13:58
S34 6	14	S342 and "205".clas.	US-PGPUB; USPAT	ADJ	ON	2007/02/06 13:58
S34 7	13	S343 and "205".clas.	US-PGPUB; USPAT	ADJ	ON	2007/02/06 13:58
S34 8	13	S344 and "205".clas.	US-PGPUB; USPAT	ADJ	ON	2007/02/06 14:05
S35 0	6	S346 and "204".clas.	US-PGPUB; USPAT	ADJ	ON	2007/02/06 13:59
S35 3	1	"6943112".pn.	US-PGPUB; USPAT	ADJ	ON	2007/02/07 13:54
S35 4	1	"6921551".pn.	US-PGPUB; USPAT	ADJ	ON	2007/02/07 13:54
S35 5	1	"6709563".pn.	US-PGPUB; USPAT	ADJ	ON	2007/02/07 18:03
S35 6	8888	(substrate and electroplating and seed layer and void or voids and (fill or filled or filling)) and (aspect ratio)	US-PGPUB; USPAT	ADJ	ON	2007/02/08 16:16

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S35 7	749	S356 and organic adj compound	US-PGPUB; USPAT	ADJ	ON	2007/02/08 15:37
S35 8	292	S357 and sulfur	US-PGPUB; USPAT	ADJ	ON	2007/02/08 15:38
S35 9	76	S357 and sulfur and accelerator	US-PGPUB; USPAT	ADJ	ON	2007/02/08 15:38
S36 0	14	S356 and (reverse electric field)	US-PGPUB; USPAT	ADJ	ON	2007/02/08 16:17
S36 1	1	"6709563".pn.	US-PGPUB; USPAT	ADJ	ON	2007/02/12 07:36
S36 2	1	"6943112".pn.	US-PGPUB; USPAT	ADJ	ON	2007/02/12 07:36
S36 3	160	(((substrate and electroplating and seed layer and void or voids and (fill or filled or filling)) and (aspect ratio))) and (current adj density)) and (plating adj rate)	US-PGPUB; USPAT	ADJ	ON	2007/02/12 15:37
S36 4	39	S363 and (anode same voltage)	US-PGPUB; USPAT	ADJ	ON	2007/02/12 12:11
S36 5	31	S363 and (anode same (cathode or substrate) same volt\$3)	US-PGPUB; USPAT	ADJ	ON	2007/02/12 15:38
S36 6	1	"6632335".pn.	US-PGPUB; USPAT	ADJ	ON	2007/02/12 16:34
S36 7	1	"7033463".pn.	US-PGPUB; USPAT	ADJ	ON	2007/02/14 11:32
S36 8	1	"6632335".pn.	US-PGPUB; USPAT	ADJ	ON	2007/02/14 13:56

Searches for User *tpatel3* (Count = 276)

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S #	Updt	Database	Query	Time	Comment
<u>S176</u>	<u>U</u>	PGPB,USPT	metal	2007-02-02 09:06:28	
<u>S175</u>	<u>U</u>	PGPB,USPT	(recess or via or trench or trenches)	2007-02-02 09:05:47	
<u>S174</u>	<u>U</u>	PGPB,USPT	plating adj method	2007-02-02 09:05:12	
<u>S173</u>	<u>U</u>	PGPB,USPT	substrate	2007-02-02 09:03:22	
<u>S172</u>	<u>U</u>	PGPB,USPT	6632335.pn.	2007-02-02 08:18:20	
<u>S171</u>	<u>U</u>	PGPB,USPT	6806186.pn.	2007-02-02 08:18:09	
<u>S170</u>	<u>U</u>	PGPB,USPT	5942097.pn.	2007-01-30 16:10:40	
<u>S169</u>	<u>U</u>	USPT	(5942097.pn.) AND @pd>20070130	2007-01-30 16:08:49	
<u>S168</u>	<u>U</u>	PGPB,USPT	(5942097.pn.) AND @pd>20070130	2007-01-30 16:02:03	
<u>S167</u>	<u>U</u>	PGPB,USPT	5942097.pn.	2007-01-30 14:15:10	
<u>S166</u>	<u>U</u>	USPT	5942097.pn.	2007-01-30 14:14:45	
<u>S165</u>	<u>U</u>	USPT	(204.clas. or 205.clas. and (anode with frame)) and (non near2 consumable)	2007-01-30 14:01:44	
<u>S164</u>	<u>U</u>	USPT	(204.clas. or 205.clas. and (anode with frame)) and (non-consumable adj anode)	2007-01-30 14:00:15	
<u>S163</u>	<u>U</u>	USPT	EP-195143-\$.did.	2007-01-30 13:27:03	
<u>S162</u>	<u>U</u>	USPT	(204.clas. or 205.clas. and (anode with frame) and (modif\$8) and (interface)) and (adjust\$5)	2007-01-30 11:49:11	
<u>S161</u>	<u>U</u>	USPT	(204.clas. or 205.clas. and (anode with frame) and (modif\$8)) and (interface)	2007-01-30 11:48:38	
<u>S160</u>	<u>U</u>	USPT	(204.clas. or 205.clas. and (anode with frame)) and (modif\$8)	2007-01-30 11:47:29	

<u>S159</u>	<u>U</u>	USPT	(204.clas. or 205.clas.) and (anode with frame)	2007-01-30 11:46:41
<u>S158</u>	<u>U</u>	USPT	(204.clas.) or (205.clas.)	2007-01-30 11:46:05
<u>S157</u>	<u>U</u>	USPT	(204.clas.) and (205.clas.)	2007-01-30 11:45:56
<u>S156</u>	<u>U</u>	USPT	(204.clas.) and l31L31	2007-01-30 11:45:45
<u>S155</u>	<u>U</u>	USPT	205.clas.	2007-01-30 11:45:37
<u>S154</u>	<u>U</u>	USPT	204.clas.	2007-01-30 11:45:30
<u>S153</u>	<u>U</u>	USPT	(amd and (distance) and (alumina) and reduction and (mobile)) and (mobile with anode)	2007-01-30 11:42:33
<u>S152</u>	<u>U</u>	USPT	(amd and (distance) and (alumina) and reduction) and (mobile)	2007-01-30 11:42:03
<u>S151</u>	<u>U</u>	USPT	(amd and (distance) and (alumina)) and reduction	2007-01-30 11:41:29
<u>S150</u>	<u>U</u>	USPT	(amd and (distance)) and (alumina)	2007-01-30 11:41:16
<u>S149</u>	<u>U</u>	USPT	(amd and (distance)) (alumina)	2007-01-30 11:41:09
<u>S148</u>	<u>U</u>	USPT	(amd) and (distance)	2007-01-30 11:40:57
<u>S147</u>	<u>U</u>	USPT	amd	2007-01-30 11:40:18
<u>S146</u>	<u>U</u>	USPT	((interface condition)) and (anode same bath)	2007-01-30 11:34:29
<u>S145</u>	<u>U</u>	USPT	anode same bath	2007-01-30 11:34:20
<u>S144</u>	<u>U</u>	USPT	(interface condition)	2007-01-30 11:34:03
<u>S143</u>	<u>U</u>	USPT,PGPB	('3909375' '4151061' '4405433' '4592812' '4707239' '4865701' '5006209' '5284562' '5368702' '5378325' '6093304')![pn]	2007-01-30 11:25:27
<u>S142</u>	<u>U</u>	USPT	((alumina with dissolution with rate)) and (gas near bubbles)	2007-01-30 11:23:09
<u>S141</u>	<u>U</u>	USPT	((alumina with dissolution with rate)) and (anode same frame)	2007-01-30 11:22:46
<u>S140</u>	<u>U</u>	USPT	((alumina with dissolution with rate)) (anode same frame)	2007-01-30 11:22:16
<u>S139</u>	<u>U</u>	USPT	(alumina with dissolution with rate)	2007-01-30 11:22:02
<u>S138</u>	<u>U</u>	USPT	(alumina with dissolution with rate) and (anode with frame)	2007-01-30 11:21:44
<u>S137</u>	<u>U</u>	USPT	(alumina with dissolution with rate) and (anode with frame with (mobile or displace or displaced))	2007-01-30 11:21:02

<u>S136</u>	<u>U</u>	USPT	(alumina with dissolution with rate) and (anode same frame same (mobile or displace or displaced))	2007-01-30 11:20:32
<u>S135</u>	<u>U</u>	USPT	(((((alumina with dissolution with rate same (bath)) and (measure or measured or measuring))) and (anode with gas)	2007-01-30 10:42:25
<u>S134</u>	<u>U</u>	USPT	(((((alumina with dissolution with rate same (bath)) and (measure or measured or measuring))) and (displac\$5)	2007-01-30 10:40:28
<u>S133</u>	<u>U</u>	USPT	(((((alumina with dissolution with rate same (bath)) and (measure or measured or measuring))) and (intervention)	2007-01-30 10:39:54
<u>S132</u>	<u>U</u>	USPT	(((((alumina with dissolution with rate same (bath)) and (measure or measured or measuring))) and (displac\$5 same anode)	2007-01-30 10:39:26
<u>S131</u>	<u>U</u>	USPT	(((((alumina with dissolution with rate same (bath)) and (measure or measured or measuring)))	2007-01-30 10:38:39
<u>S130</u>	<u>U</u>	USPT	((("6245201" "4935107" "6221233")!.PN.)) AND @pd>20070130	2007-01-30 10:17:15
<u>S129</u>	<u>U</u>	PGPB,USPT	(6245201.pn.) AND @pd>20070130	2007-01-30 09:42:34
<u>S128</u>	<u>U</u>	PGPB,USPT	6245201.pn.	2007-01-30 09:40:38
<u>S127</u>	<u>U</u>	USPT	6245201.pn.	2007-01-30 09:40:16

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<u>S226</u>	<u>U</u>	PGPB,USPT	metal same plating	2007-02-06 14:57:15	
<u>S225</u>	<u>U</u>	PGPB,USPT	filling or fill or filled	2007-02-06 14:56:52	
<u>S224</u>	<u>U</u>	PGPB,USPT	substrate	2007-02-06 14:56:09	
<u>S223</u>	<u>U</u>	PGPB,USPT	plating	2007-02-06 14:56:01	
<u>S222</u>	<u>U</u>	PGPB,USPT	(substrate and plating and (metal interconnect) and recess) and 205.clas.	2007-02-06 14:47:28	
<u>S221</u>	<u>U</u>	PGPB,USPT	(substrate and plating and (metal interconnect)) and recess	2007-02-06 14:46:58	
<u>S220</u>	<u>U</u>	PGPB,USPT	(substrate and plating and (metal interconnect)) and narrow adj recess	2007-02-06 14:46:32	
<u>S219</u>	<u>U</u>	PGPB,USPT	(substrate and plating and (metal interconnect)) and (narrow recess or broad recess)	2007-02-06 14:46:20	
<u>S218</u>	<u>U</u>	PGPB,USPT	(substrate and plating and (metal interconnect)) and (recess or trench)	2007-02-06 14:45:30	
<u>S217</u>	<u>U</u>	PGPB,USPT	(substrate and plating and (metal interconnect) and (recess or via or trench) and (narrow or broad)) and 205.clas.	2007-02-06 14:40:11	
<u>S216</u>	<u>U</u>	PGPB,USPT	(substrate and plating and (metal interconnect) and (recess or via or trench)) and (narrow or broad)	2007-02-06 14:39:13	
<u>S215</u>	<u>U</u>	PGPB,USPT	(substrate and plating and (metal interconnect)) and	2007-02-	

		(recess or via or trench)	06 14:37:25
<u>S214</u>	<u>U</u>	PGPB,USPT substrate and plating and (metal interconnect)	2007-02-06 14:35:36
<u>S213</u>	<u>U</u>	PGPB,USPT (substrate) and (plating adj method)	2007-02-06 14:09:13
<u>S212</u>	<u>U</u>	PGPB,USPT (substrate) and (plating adj method) and (metal near interconnect)	2007-02-06 14:09:00
<u>S211</u>	<u>U</u>	PGPB,USPT substrate and (plating adj method) and (interconnect adj metal)	2007-02-06 14:08:31
<u>S210</u>	<u>U</u>	PGPB,USPT substrate and (plating adj method) and (interconnect metal)	2007-02-06 14:08:13
<u>S209</u>	<u>U</u>	PGPB,USPT substrate and (plating adj method) and (interconnect metal)	2007-02-06 14:08:09
<u>S208</u>	<u>U</u>	PGPB,USPT substrate and (plating adj method) and (interconnect metal) and (via or trench or recess) and (narrow or small or thin) and (fill or filled or filling or deposit or deposited or depositng) and (broad or wide or deep)	2007-02-06 14:07:51
<u>S207</u>	<u>U</u>	PGPB,USPT substrate and (plating adj method) and (interconnect metal) and (via or trench or recess) and (narrow or small or thin) and (fill or filled or filling or deposit or deposited or depositng) and (broad or wide or deep)	2007-02-06 14:07:24
<u>S206</u>	<u>U</u>	PGPB,USPT (substrate and plating adj method and semiconductor) and ((recess or via or trench))	2007-02-06 13:39:16
<u>S205</u>	<u>U</u>	PGPB,USPT (substrate and interconnect metal and semiconductor) and ((recess or via or trench))	2007-02-06 13:37:42
<u>S204</u>	<u>U</u>	PGPB,USPT (substrate and plating adj method) and (semiconductor)	2007-02-06 13:35:37
<u>S203</u>	<u>U</u>	PGPB,USPT (substrate and interconnect metal) and (semiconductor)	2007-02-06 13:33:15
<u>S202</u>	<u>U</u>	PGPB,USPT (substrate) and (plating adj method)	2007-02-06 13:15:44
<u>S201</u>	<u>U</u>	PGPB,USPT (substrate) and (plating adj method)	2007-02-06 13:13:56

<u>S200</u>	<u>U</u>	PGPB,USPT (substrate) and (interconnect metal)	2007-02-06 13:12:07
<u>S199</u>	<u>U</u>	PGPB,USPT interconnect adj metal	2007-02-06 13:11:52
<u>S198</u>	<u>U</u>	PGPB,USPT broad or wide or deep	2007-02-06 13:11:09
<u>S197</u>	<u>U</u>	PGPB,USPT (narrow or small or thin or pinched or close)	2007-02-06 13:10:11
<u>S196</u>	<u>U</u>	PGPB,USPT semiconductor	2007-02-06 13:08:13
<u>S195</u>	<u>U</u>	PGPB,USPT (recess or via or trench)	2007-02-06 13:07:12
<u>S194</u>	<u>U</u>	PGPB,USPT (recess via trench)	2007-02-06 13:06:40
<u>S193</u>	<u>U</u>	PGPB,USPT plating adj method	2007-02-06 13:05:44
<u>S192</u>	<u>U</u>	PGPB,USPT interconnect metal	2007-02-06 13:05:27
<u>S191</u>	<u>U</u>	PGPB,USPT substrate	2007-02-06 13:04:39
<u>S190</u>	<u>U</u>	PGPB,USPT (hiroyuki kanda).in. or (mizuki nagai).in. or (satoru yamamoto).in.	2007-02-06 13:02:58
<u>S189</u>	<u>U</u>	PGPB,USPT (substrate and (plating adj method) and metal and (via or trench or recess) and (narrow or small or pinched) and (broad or wide or deep) and (aspect adj ratio) and (seed layer)) and copper	2007-02-02 09:25:24
<u>S188</u>	<u>U</u>	PGPB,USPT (substrate and (plating adj method) and metal and (via or trench or recess) and (narrow or small or pinched) and (broad or wide or deep) and (aspect adj ratio)) and (seed layer)	2007-02-02 09:22:52
<u>S187</u>	<u>U</u>	PGPB,USPT (substrate and (plating adj method) and metal and (via or trench or recess) and (narrow or small or pinched) and (broad or wide or deep)) and (aspect adj ratio)	2007-02-02 09:21:14
<u>S186</u>	<u>U</u>	PGPB,USPT (substrate and (plating adj method) and metal and (via or trench or recess) and (narrow or small or pinched) and (broad or wide or deep)) (aspect adj	2007-02-02 09:21:07

		ratio)	
<u>S185</u>	<u>U</u>	PGPB,USPT (substrate and (plating adj method) and metal and (via or trench or recess) and (narrow or small or pinched)) and (broad or wide or deep)	2007-02-02 09:17:58
<u>S184</u>	<u>U</u>	PGPB,USPT (substrate and (plating adj method) and metal and (via or trench or recess)) and (narrow or small or pinched)	2007-02-02 09:16:39
<u>S183</u>	<u>U</u>	PGPB,USPT (substrate and (plating adj method) and metal) and (via or trench or recess)	2007-02-02 09:14:53
<u>S182</u>	<u>U</u>	PGPB,USPT substrate and (plating adj method) and metal	2007-02-02 09:13:56
<u>S181</u>	<u>U</u>	PGPB,USPT (substrate) and (plating adj method) and (metal)	2007-02-02 09:12:41
<u>S180</u>	<u>U</u>	PGPB,USPT (substrate) and (plating adj method) and (metal)	2007-02-02 09:11:03
<u>S179</u>	<u>U</u>	PGPB,USPT (substrate) and (plating adj method) and (metal)	2007-02-02 09:09:27
<u>S178</u>	<u>U</u>	PGPB,USPT (broad or wide or deep)	2007-02-02 09:08:51
<u>S177</u>	<u>U</u>	PGPB,USPT (narrow or small or thin or pinched or close)	2007-02-02 09:07:28

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<u>S276</u>	<u>U</u>	PGPB,USPT	(((((substrate and electroplating and seed layer and void or voids and (fill or filled or filling)) and (aspect ratio))) and (current adj density)) and (plating adj rate)	2007-02-12 08:30:07	
<u>S275</u>	<u>U</u>	USPT,PGPB	('6531046' '20020000382' '20020043467' '20020043468')![pn]	2007-02-08 15:32:58	
<u>S274</u>	<u>U</u>	PGPB,USPT	((substrate and electroplating and seed layer and void or voids and (fill or filled or filling)) and (aspect ratio)) and (organic same accelerator)	2007-02-08 15:13:20	
<u>S273</u>	<u>U</u>	PGPB,USPT	((substrate and electroplating and seed layer and void or voids and (fill or filled or filling)) and (aspect ratio)) and (organic adj compund same accelerator)	2007-02-08 15:12:49	
<u>S272</u>	<u>U</u>	PGPB,USPT	((substrate and electroplating and seed layer and void or voids and (fill or filled or filling)) and (aspect ratio)) and organic compound	2007-02-08 15:11:54	
<u>S271</u>	<u>U</u>	PGPB,USPT	(nagai.in.) and mizuki	2007-02-08 15:04:21	
<u>S270</u>	<u>U</u>	PGPB,USPT	nagai.in.	2007-02-08 15:04:12	
<u>S269</u>	<u>U</u>	PGPB,USPT	(satoru yamamoto).in.	2007-02-08 15:03:33	
<u>S268</u>	<u>U</u>	PGPB,USPT	satoru adj yamamoto.in.	2007-02-08 15:03:12	
<u>S267</u>	<u>U</u>	PGPB,USPT	mizuki adj nagai.in.	2007-02-08 15:02:55	
<u>S266</u>	<u>U</u>	PGPB,USPT	(mizuki nagai).in.	2007-02-08	

<u>S265</u>	<u>U</u>	PGPB,USPT(hiroyuki kanda).in.	15:02:31 2007-02-08 14:56:15
<u>S264</u>	<u>U</u>	PGPB,USPT kanda.in.	2007-02-08 14:55:20
<u>S263</u>	<u>U</u>	PGPB,USPT(((substrate and electroplating and seed layer and void or voids and (fill or filled or filling)) and (aspect ratio)) and ((catalyst or accelerator) with organic)	2007-02-08 14:26:47
<u>S262</u>	<u>U</u>	PGPB,USPT(substrate and electroplating and seed layer and void or voids and (fill or filled or filling)) and (aspect ratio)	2007-02-08 14:22:19
<u>S261</u>	<u>U</u>	PGPB,USPT 6943112.pn.	2007-02-08 08:21:44
<u>S260</u>	<u>U</u>	PGPB,USPT((((substrate and electroplating and seed layer and void or voids and (fill or filled or filling)) and (aspect ratio))) and (current adj density)) and (plating adj rate)	2007-02-08 07:56:57
<u>S259</u>	<u>U</u>	PGPB,USPT((((substrate and electroplating and seed layer and void or voids and (fill or filled or filling)) and (aspect ratio))) and (current adj density)) and (current adj density same progressively)	2007-02-08 07:40:23
<u>S258</u>	<u>U</u>	PGPB,USPT((((substrate and electroplating and seed layer and void or voids and (fill or filled or filling)) and (aspect ratio))) and (current adj density)) and progressively	2007-02-08 07:39:55
<u>S257</u>	<u>U</u>	PGPB,USPT(((substrate and electroplating and seed layer and void or voids and (fill or filled or filling)) and (aspect ratio))) and (current adj density)	2007-02-08 07:32:39
<u>S256</u>	<u>U</u>	PGPB,USPT(((substrate and electroplating and seed layer and void or voids and (fill or filled or filling)) and (aspect ratio))) and (cm.sup.2 or dm.sup.2)	2007-02-07 17:45:41
<u>S255</u>	<u>U</u>	PGPB,USPT(((substrate and electroplating and seed layer and void or voids and (fill or filled or filling)) and (aspect ratio))) and (A\$cm.sup.2)	2007-02-07 17:45:25
<u>S254</u>	<u>U</u>	PGPB,USPT(((substrate and electroplating and seed layer and void or voids and (fill or filled or filling)) and (aspect ratio))) and (A/cm.sup.2)	2007-02-07 17:45:01
<u>S253</u>	<u>U</u>	PGPB,USPT(((substrate and electroplating and seed layer and void or voids and (fill or filled or filling)) and (aspect ratio))) and (A/cm.sup.2 or A/dm.sup.2)	2007-02-07 17:44:45
<u>S252</u>	<u>U</u>	PGPB,USPT(((substrate and electroplating and seed layer and void or voids and (fill or filled or filling)) and (aspect ratio))) and (current adj density)	2007-02-07 17:41:56
<u>S251</u>	<u>U</u>	PGPB,USPT(((substrate and electroplating and seed layer and	2007-02-

		void or voids and (fill or filled or filling)) and (aspect ratio))) and A/	07 17:36:09
<u>S250</u>	<u>U</u>	PGPB,USPT(((substrate and electroplating and seed layer and void or voids and (fill or filled or filling)) and (aspect ratio))) and A/	2007-02-07 17:36:03
<u>S249</u>	<u>U</u>	PGPB,USPT(substrate and electroplating and seed layer and void or voids and (fill or filled or filling)) and (aspect ratio)	2007-02-07 17:35:27
<u>S248</u>	<u>U</u>	PGPB,USPT 6077780.pn.	2007-02-07 16:06:49
<u>S247</u>	<u>U</u>	PGPB,USPT(substrate and electroplating and seed layer and void or voids and (fill or filled or filling)) and (small aspect ratio)	2007-02-06 17:32:19
<u>S246</u>	<u>U</u>	PGPB,USPT(substrate and electroplating and seed layer and void or voids and (fill or filled or filling) and (aspect ratio)) and recess	2007-02-06 15:38:14
<u>S245</u>	<u>U</u>	PGPB,USPT(substrate and electroplating and seed layer and void or voids and (fill or filled or filling)) and (aspect ratio)	2007-02-06 15:35:17
<u>S244</u>	<u>U</u>	PGPB,USPT(substrate and electroplating and seed layer and void or voids) and (fill or filled or filling)	2007-02-06 15:25:57
<u>S243</u>	<u>U</u>	PGPB,USPT(substrate and electroplating and seed layer and void or voids) and (deposit\$4)	2007-02-06 15:24:18
<u>S242</u>	<u>U</u>	PGPB,USPT(substrate and electroplating and seed layer) and (void or voids)	2007-02-06 15:22:21
<u>S241</u>	<u>U</u>	PGPB,USPT(substrate) and (electroplating) and (seed layer)	2007-02-06 15:20:01
<u>S240</u>	<u>U</u>	PGPB,USPT seed layer	2007-02-06 15:19:26
<u>S239</u>	<u>U</u>	PGPB,USPT void or voids	2007-02-06 15:18:36
<u>S238</u>	<u>U</u>	PGPB,USPT electroplating	2007-02-06 15:18:05
<u>S237</u>	<u>U</u>	PGPB,USPT substrate	2007-02-06 15:17:06
<u>S236</u>	<u>U</u>	PGPB,USPT(plating and (aspect adj ratio) and substrate and (fill or filled or filling)) and (large or small)	2007-02-06 15:10:09
<u>S235</u>	<u>U</u>	PGPB,USPT(plating and (aspect adj ratio) and substrate) and	2007-02-

	(fill or filled or filling)	06
		15:09:19
<u>S234</u>	<u>U</u> PGPB,USPT (plating and (aspect adj ratio)) and substrate	2007-02-
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		15:07:04
<u>S233</u>	<u>U</u> PGPB,USPT plating and (aspect adj ratio)	2007-02-
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		15:06:31
<u>S232</u>	<u>U</u> PGPB,USPT (second plating) and (broad adj (recess or trench))	2007-02-
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		15:05:08
<u>S231</u>	<u>U</u> PGPB,USPT (plating) and (second plating)	2007-02-
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		15:04:41
<u>S230</u>	<u>U</u> PGPB,USPT broad adj (recess or trench)	2007-02-
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		14:58:52
<u>S229</u>	<u>U</u> PGPB,USPT broad (recess or trench)	2007-02-
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		14:58:44
<u>S228</u>	<u>U</u> PGPB,USPT narrow adj (recess or trench)	2007-02-
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		14:58:24
<u>S227</u>	<u>U</u> PGPB,USPT second plating	2007-02-
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		14:57:50

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